

PROCESSING APPARATUS

ABSTRACT OF THE DISCLOSURE

A grinding apparatus has an annular space produced as a hermetically sealed chamber jointly defined by a portion of a holding surface which extends radially outwardly from a wafer, an outer wall surface of a first annular packing, a lower surface of a plate, and an inner wall surface of a second annular packing. A negative pressure is developed in the annular space due to suction forces applied from the holding surface, for thereby allowing the atmospheric pressure to press the plate toward the holding surface and causing the first annular packing to press an outer circumferential portion of the wafer against the holding surface. Since the outer circumferential portion of the wafer is pressed against the holding surface under the suction forces from the holding surface and the atmospheric pressure, the forces with which to press the outer circumferential portion of the wafer against the holding surface are increased easily at a low cost without involving an increase in the size and weight of the grinding apparatus.

[Fig. 5]